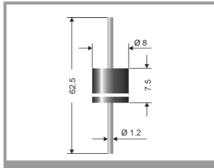
# SB 3020 ... SB 3065



**Axial Lead Diode** 

Schottky barrier rectifier diodes

Forward Current: 30 A

Reverse Voltage: 20 to 65 V

SB 3020 ... SB 3065

Preliminary Data

#### **Features**

- Max. solder temperature: 260°C
- Plastic material has UL classification 94V-0

### Typical Applications\*

- Designed as Bypass Diodes for Solar Panels
- · Protection application

#### **Mechanical Data**

- Plastic case: 8 x 7.5 [mm]
- Weight approx.: 1.5 g
- Terminals: plated terminals solderable per MIL-STD-750
- · Mounting position: any
- Standard packaging: 500 pieces per ammo or 1000 pieces per reel

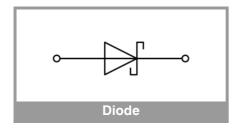
#### **Footnotes**

- $^{1)}$   $I_F = -A$ ,  $I_R = -A$ ,  $I_{RR} = -A$
- <sup>2)</sup>  $I_F = 5A$ ,  $T_j = 25$  °C
- $^{3)}$   $I_F=30$  A,  $T_j=25\ ^{\circ}C$
- $^{4)}$  Valid, if leads are kept at  $T_A$  at a distance of 0 mm from case
- $^{5)}$  Max. junction temperature T $_{j}$   $\leq$  150 °C (VR  $\leq$  80%  $_{VRRM}$ ) in reverse mode and T $_{J}$   $\leq$  200 °C in bypass mode
- <sup>6)</sup> Thermal resistance from junction to lead/ terminal at distance 0 mm from case

Туре	Repetitive peak reverse voltage V <sub>RRM</sub> V	Surge peak reverse voltage V <sub>RSM</sub> V	Max. reverse recovery time  t <sub>rr</sub> <sup>1)</sup> ns	Max. forward voltage V <sub>F</sub> <sup>2)</sup> V	Max. forward voltage V <sub>F</sub> <sup>3)</sup>
SB 3020	20	20	-	0.37	0.5
SB 3030	30	30	-	0.37	0.5
SB 3040	40	40	-	0.37	0.5
SB 3050	50	50	-	0.5	0.65
SB 3060	60	60	-	0.5	0.65
SB 3065	65	65	-	0.5	0.65

Absolute Maximum Ratings								
Symbol	Conditions		Values	Unit				
Ta = 25 °C	c, unless otherwis	e specified	•	•				
I <sub>FAV</sub>	R-load, $^{4)}$ , $T_a = 50  ^{\circ}\text{C}$		30	Α				
I <sub>FRM</sub>	f > 15 Hz, <sup>4)</sup>		90	Α				
	half sinus-wave	t <sub>p</sub> = 10 ms	700	Α				
	T <sub>a</sub> = 25 °C	$t_p = 8.3 \text{ ms}$		Α				
i <sup>2</sup> t	T <sub>a</sub> = 25 °C	$t_p = 10 \text{ ms}$	2450	A <sup>2</sup> s				
		$t_p = 8.3 \text{ ms}$		A <sup>2</sup> s				
Tj	Operating junction temperature		-50 +150	°C				
Tj	DC forward (bypass) mode 5)		-50 <b>+</b> 200	°C				
T <sub>stg</sub>	Storage temperature		-50 +175	°C				

Characteristics							
Symbol	Conditions	min.	typ.	max.	Unit		
Ta = 25 °C, unless otherwise specified							
I <sub>R</sub>	$T_j = 25 ^{\circ}\text{C},  V_R = V_{RRM}$			600	μΑ		
I <sub>R</sub>	$T_j = 100  ^{\circ}\text{C},  V_R = V_{RRM}$		35		mA		
C <sub>j</sub>	at 1 MHz and applied reverse voltage of 4 V		-		pF		
E <sub>RSM</sub>	$L = 60$ mH, $T_j = 25$ °C, inductive load switched off		-		mJ		
R <sub>th(j-a)</sub>	4)			-	K/W		
R <sub>th(j-L)</sub>	6)			2.5	K/W		



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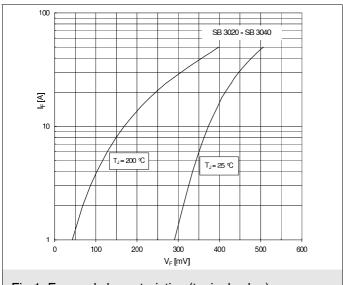


Fig.1: Forward characteristics (typical value)

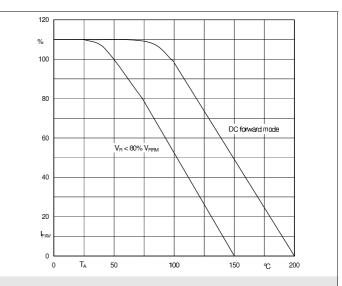


Fig.2: Rated forward current vs. ambient temperature 1)

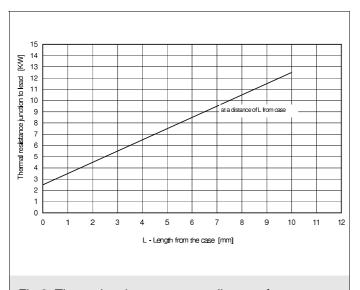
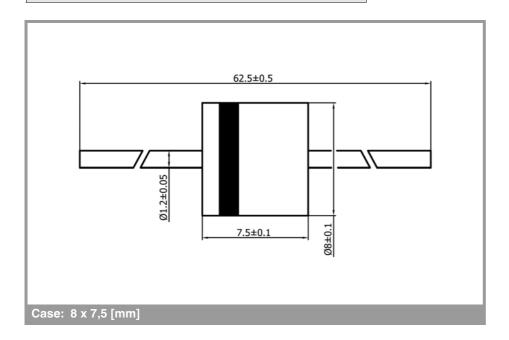


Fig.3: Thermal resistance versus distance from case



### SB 3020 ... SB 3065

This is an electrostatic discharge sensitive device (ESDS), international standard IEC 60747-1, Chapter IX

\* The specifications of our components may not be considered as an assurance of component characteristics. Components have to be tested for the respective application. Adjustments may be necessary. The use of SEMIKRON products in life support appliances and systems is subject to prior specification and written approval by SEMIKRON. We therefore strongly recommend prior consultation of our staff.